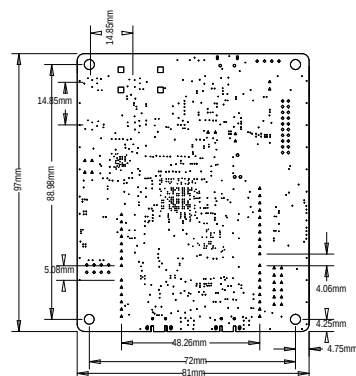
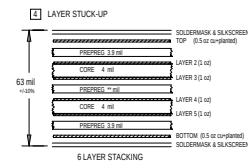


REVISIONS			
REV	DESCRIPTION	DATE	APPROVE
1.0	EDITION ORIGINALE	2008-04-09	xxx

5 IMPEDANCE TABLE

LAYER	TRACE (mil)	SPACING (mil)	IMPEDANCE (Single end)	IMPEDANCE (Differential)	TOLERANCE
1,5	5.0	N/A	55 OHM	N/A	+/-10%
4	4.0		N/A	100 OHM	+/-10%
1,6	6.1	8.9	N/A	90 OHM	+/-10%



DRILL CHART: TOP IS BOTTOM						
ALL UNITS ARE IN MILS						
FIGURE	SIZE	TOLERANCE	PLATED	ROTATION	QTY	
•	6.0	+0.0/-3.0	PLATED	-	35	
•	8.0	+0.0/-3.0	PLATED	-	196	
•	10.0	+0.0/-3.0	PLATED	-	231	
•	12.0	+0.0/-3.0	PLATED	-	393	
•	33.0	+0.0/-3.0	PLATED	-	2	
•	36.0	+0.0/-3.0	PLATED	-	52	
•	40.0	+0.0/-3.0	PLATED	-	34	
○	138.0	+0.0/-3.0	PLATED	-	4	
•	39.0	+0.0/-2.0	NON-PLATED	-	3	
□	79.0	+0.0/-2.0	NON-PLATED	-	4	
•	138.0	+0.0/-2.0	NON-PLATED	-	1	
•	33.0x30.0	+0.0/-0.0	PLATED	90.000	4	
•	51.0x20.0	+0.0/-0.0	PLATED	90.000	2	
•	59.0x33.0	+0.0/-0.0	PLATED	90.000	4	
TOTAL HOLE FS					964	

PCB SPECIFICATIONS:

- | | | | | |
|---|---|--|--|---------------------------------|
| A. MATERIAL: | FR-4 | ☒ TG-170 | ☐ TG-150 | ☐ TG-140 |
| B. MATERIAL FAMILY: | N/A | | | |
| C. SOLDERMASK COLOR: | ☒ GREEN | ☐ BLUE | ☐ RED | ☐ BLACK |
| D. SILKSCREEN COLOR: | ☒ WHITE | ☐ YELLOW | ☐ BLACK | |
| E. SURFACE FINISH: | ☒ ENIG | ☐ IMMERSION SILVER | ☐ IMMERSION TIN | |
| | ☐ HASL | ☐ HASL(PB-FREE) | ☐ GOLDEN FINGER | |
| ☐ IMPEDANCE CONTROL: | ☐ NO | ☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION) | | |
| G. THROUGH VIA: | | PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDES. | | |
| | | PLUG MATERIAL: ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY. | | |
| H. STACK-UP: | | USE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS. | | |

PCB REQUIREMENTS:

1. THIS BOARD WILL CONFORM TO:
IPC-A-600, CURRENT REV. CLASS II
IPC-6012, CURRENT REV. CLASS II
2. UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING.
ALL HOLES SHALL BE LOC'D WITHIN .002" DIAMETER OF TRUE POSITION.
3. PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN .001 INCH MINIMUM
AVERAGE, WITH NO READING LESS THAN .0008 BY CORROSION SECTION.
4. MATERIAL: FRATING 94V-0 MONOLAYER EPOXY GLASS LAMINATE.
5. BOARD SHALL BE LPI SOLDER MASKED OVER BARE COPPER BOTH SIDES PER
IPC-3510 CLASS II.
6. SILKSCREEN SHALL BE PERMANENT NON-CONDUCTIVE INK AND WITH NO OVERLAP
ON ANY COMPONENT PAD OR THROUGH HOLE.
7. MFG. TO LEGIBLY ETCH OR STAMPSCREEN WITH PERMANENT NON-CONDUCTIVE INK:
A. ULL CODE
B. DATE CODE
C. SUCCESSFUL ELECTRICAL BOARD TEST.
C. FLAMMABILITY RATING
8. REMOVE THE FLASHS WHICH MAY BE WITH HOLE SIZE.
9. REMOVE ALL SHAPE EDGES AND BURRS .005" MAXIMUM.
10. PLEASE USE THE SUPPLIED PIC 32C NETLIST TO VERIFY BOARD BEFORE
FABRICATING BOARD.

 DESIGNED BY SOFER www.sofer.com.cn Tel : +86 21-6482 6908 Mail: design@sofer.com.cn	LAYER: FAB DAWNING & DRILL LEGEND	COMPANY NAME: ST	PROJECT NAME: MB1260	PROJECT NUMBER: P001-02244	REV
	DESIGNER: Shelly	DATE: 2016.12.29			

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	LOGO		COMPANY NAME			
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS + 3 PL DECIMALS + ANGLES + FRACTIONS +	DRAWN	YY-MM-DD	TITLE PROJECT NAME *					
	CHECKED	YY-MM-DD						
	ENGRG	YY-MM-DD						
	ISSUED							
			SIZE	B	DWG NO	*****	REV	**
			SCALE	1:			SHEET	1 OF 1